

June 2001 Revised August 2003

#### FIN1047

### 3.3V LVDS 4-Bit Flow-Through **High Speed Differential Driver**

#### **General Description**

This quad driver is designed for high speed interconnects utilizing Low Voltage Differential Signaling (LVDS) technology. The driver translates LVTTL signal levels to LVDS levels with a typical differential output swing of 350mV which provides low EMI at ultra low power dissipation even at high frequencies. This device is ideal for high speed transfer of clock and data.

The FIN1047 can be paired with its companion receiver, the FIN1048, or any other LVDS receiver.

#### **Features**

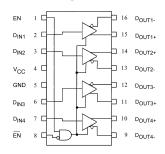
- Greater than 400Mbs data rate
- Flow-through pinout simplifies PCB layout
- 3.3V power supply operation
- 0.4 ns maximum differential pulse skew
- 1.7 ns maximum propagation delay
- Low power dissipation
- Power-Off protection
- Meets or exceeds the TIA/EIA-644 LVDS standard
- Pin compatible with equivalent RS-422 and LVPECL devices
- 16-Lead SOIC and TSSOP packages save space

#### **Ordering Code:**

Order Number	Package Number	Package Description			
FIN1047M	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow			
FIN1047MTC	MTC16	16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide			

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

#### **Connection Diagram**



#### **Truth Table**

	Inputs	Outputs			
EN EN		D <sub>IN</sub>	D <sub>OUT+</sub>	D <sub>OUT</sub>	
Н	L or OPEN	Н	Н	L	
Н	L or OPEN	L	L	Н	
Н	L or OPEN	OPEN	L	Н	
Х	Н	X	Z	Z	
L or OPEN	Х	Х	Z	Z	

H = HIGH Logic Level L = LOW Logic Level

X = Don't Care Z = High Impedance

#### **Pin Descriptions**

Pin Name	Description			
D <sub>IN1</sub> , D <sub>IN2</sub> , D <sub>IN3</sub> , D <sub>IN4</sub>	LVTTL Data Inputs			
D <sub>OUT1+</sub> , D <sub>OUT2+</sub> , D <sub>OUT3+</sub> , D <sub>OUT4+</sub>	Non-Inverting Driver Outputs			
D <sub>OUT1-</sub> , D <sub>OUT2-</sub> , D <sub>OUT3-</sub> , D <sub>OUT4-</sub>	Inverting Driver Outputs			
EN	Driver Enable Pin			
ĒN	Inverting Driver Enable Pin			
V <sub>CC</sub>	Power Supply			
GND	Ground			

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#### Absolute Maximum Ratings(Note 1)

## Recommended Operating Conditions

 $\label{eq:max_Junction} \begin{aligned} &\text{Max Junction Temperature (T_J)} & & 150^{\circ}\text{C} \\ &\text{Lead Temperature (T_L)} & & 260^{\circ}\text{C} \end{aligned}$ 

Note 1: The "Absolute Maximum Ratings": are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature and output/input loading variables. Fairchild does not recommend operation of circuits outside databook specification.

#### **DC Electrical Characteristics**

Over supply voltage and operating temperature ranges, unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ (Note 2)	Max	Units
V <sub>OD</sub>	Output Differential Voltage		250	340	450	mV
$\Delta V_{OD}$	V <sub>OD</sub> Magnitude Change from Differential LOW-to-HIGH	$R_L = 100\Omega$ , Driver Enabled,		1.4	25	mV
Vos	Offset Voltage	See Figure 1	1.125	1.25	1.375	V
ΔV <sub>OS</sub>	Offset Magnitude Change from Differential LOW-to-HIGH			1.2	25	mV
V <sub>OH</sub>	HIGH Output Voltage	$V_{IN} = V_{CC}$		1.4	1.6	V
V <sub>OL</sub>	LOW Output Voltage	$V_{IN} = 0V$	0.9	1.05		V
l <sub>OFF</sub>	Power Off Output Current	V <sub>CC</sub> = 0V, V <sub>OUT</sub> = 0V or 3.6V	-20		20	μΑ
los	Short Circuit Output Current	V <sub>OUT</sub> = 0V, Driver Enabled V <sub>OD</sub> = 0V, Driver Enabled		-3 -3.5	-6 -6	mA
V <sub>IH</sub>	Input HIGH Voltage		2.0		V <sub>CC</sub> + 1.0	V
V <sub>IL</sub>	Input LOW Voltage (Note 3)		GND		0.8	V
I <sub>IN</sub>	Input Current	V <sub>IN</sub> = 0V or V <sub>CC</sub>	-20		20	μА
l <sub>OZ</sub>	Disabled Output Leakage Current	V <sub>OUT</sub> = 0V or 4.6V	-20		20	μΑ
I <sub>I(OFF)</sub>	Power-Off Input Current	$V_{CC} = 0V, V_{IN} = 0V \text{ or } 3.6V$	-20		20	μΑ
V <sub>IK</sub>	Input Clamp Voltage	$I_{IK} = -18 \text{ mA}$	-1.5	-0.7		V
I <sub>CC</sub>	Power Supply Current	No Load, $V_{IN} = 0V$ or $V_{CC}$ , Driver Enabled		5	8	
		$R_L = 100 \Omega$ , Driver Disabled		1.7	4	mA
		$R_L$ = 100 $\Omega,V_{IN}$ = 0V or $V_{CC},Driver$ Enabled		16	22	
I <sub>PU/PD</sub>	Output Power Up/Power Down High Z Leakage Current	V <sub>CC</sub> = 0V or 1.5V	-20		20	μА

**Note 2:** All typical values are at  $T_A = 25^{\circ}C$  and with  $V_{CC} = 3.3V$ .

Note 3: For transient conditions when  $t \leq 5 ns$  and  $I_{IN} \leq -100$  mA,  $V_{ILmin} = -1.0 V.$ 

#### **AC Electrical Characteristics**

Over supply voltage and operating temperature ranges, unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ (Note 4)	Max	Units
t <sub>PLHD</sub>	Differential Propagation Delay LOW-to-HIGH		0.6	1.1	1.7	ns
t <sub>PHLD</sub>	Differential Propagation Delay		0.6	1.2	1.7	ns
t <sub>TLHD</sub>	Differential Output Rise Time (20% to 80%)	$R_L = 100 \Omega$ , $C_L = 10 pF$ ,	0.4		1.2	ns
t <sub>THLD</sub>	Differential Output Fall Time (80% to 20%)  Pulse Skew  tplh - tphl	See Figure 2 (Note 8), and Figure 3	0.4		0.4	ns ns
t <sub>SK(LH)</sub>	Channel-to-Channel Skew (Note 5)			0.05	0.3	ns
t <sub>SK(PP)</sub>	Part-to-Part Skew (Note 6)				1.0	ns
f <sub>MAX</sub>	Maximum Frequency (Note 7)	$R_L = 100\Omega$ , See Figure 6 (Note 8)	200	250		MHz
t <sub>ZHD</sub>	Differential Output Enable Time from Z to HIGH			1.7	5.0	ns
t <sub>ZLD</sub>	Differential Output Enable Time from Z to LOW	$R_L = 100\Omega$ , $C_L = 10 pF$ ,		1.7	5.0	ns
t <sub>HZD</sub>	Differential Output Disable Time from HIGH to Z	See Figure 4 (Note 8), and Figure 5		2.7	5.0	ns
t <sub>LZD</sub>	Differential Output Disable Time from LOW to Z	1		2.7	5.0	ns
C <sub>IN</sub>	Input Capacitance			4.2		pF
C <sub>OUT</sub>	Output Capacitance			5.2		pF

Note 4: All typical values are at  $T_A = 25$ °C and with  $V_{CC} = 3.3$ V.

Note 5:  $t_{SK(LH)}$ ,  $t_{SK(HL)}$  is the skew between specified outputs of a single device when the outputs have identical loads and are switching in the same direction.

Note 6:  $t_{SK(PP)}$  is the magnitude of the difference in propagation delay times between any specified terminals of two devices switching in the same direction (either LOW-to-HIGH or HIGH-to-LOW) when both devices operate with the same supply voltage, same temperature, and have identical test circuits.

Note 7:  $f_{MAX}$  criteria: Input  $t_R = t_F < 1$ ns, 0V to 3V, 50% Duty Cycle; Output  $V_{OD} > 250$  mv, 45% to 55% Duty Cycle; all switching in phase channels.

Note 8: Test Circuits in Figures 2, 4, 6 are simplified representations of test fixture and DUT loading.

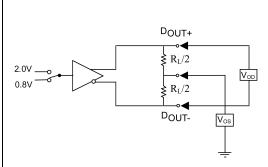
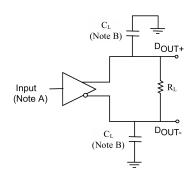


FIGURE 1. Differential Driver DC Test Circuit FIGURE 2



 $\label{eq:Note A: All input pulses have frequency = 10 MHz, $t_R$ or $t_F = 1$ ns. \\ \note B: $C_L$ includes all fixture and instrumentation capacitance$ 

FIGURE 2. Differential Driver Propagation Delay and Transition Time Test Circuit

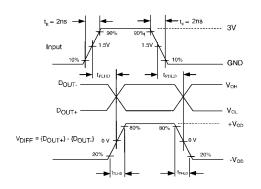
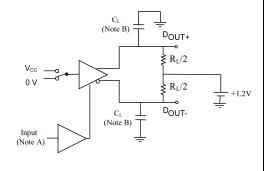


FIGURE 3. AC Waveforms



Note B: All input pulses have the frequency = 10 MHz,  $t_R$  or  $t_F$  = 1 ns

Note A:  $\mathbf{C}_{\mathsf{L}}$  includes all fixture and instrumentation capacitance

FIGURE 4. Differential Driver Enable and Disable Test Circuit

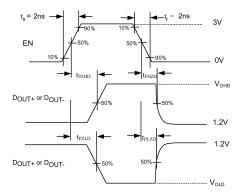


FIGURE 5. Enable and Disable AC Waveforms

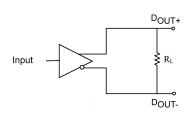
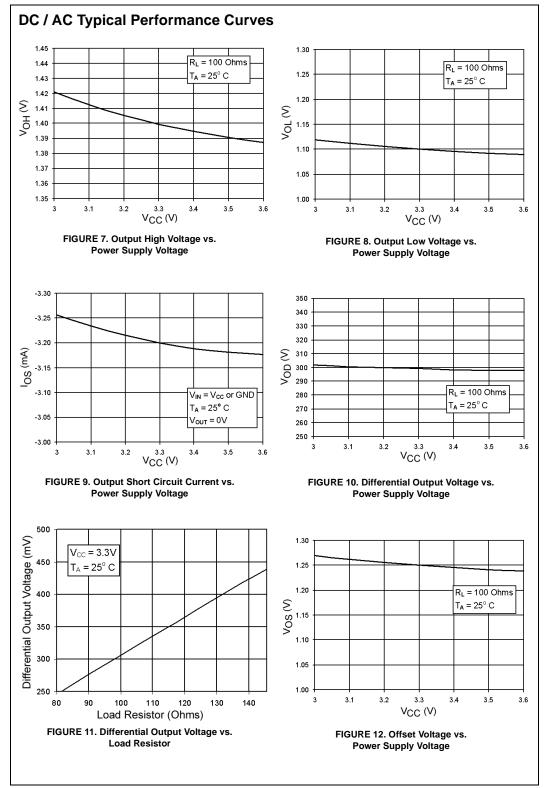
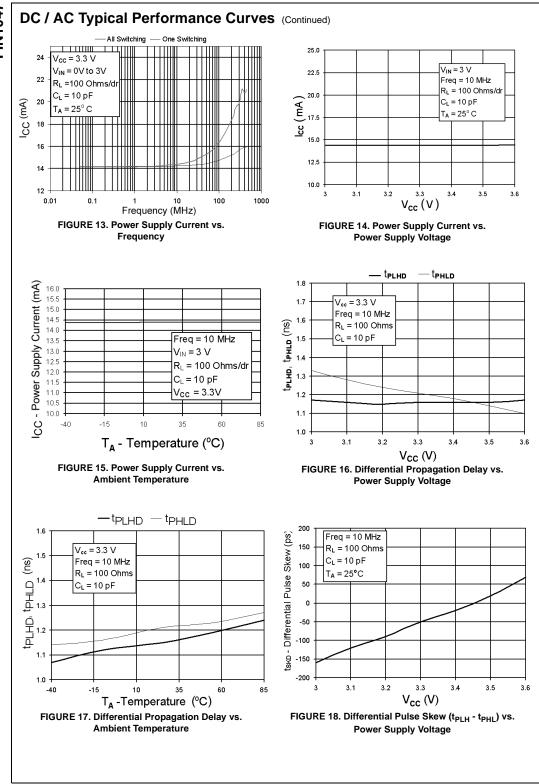
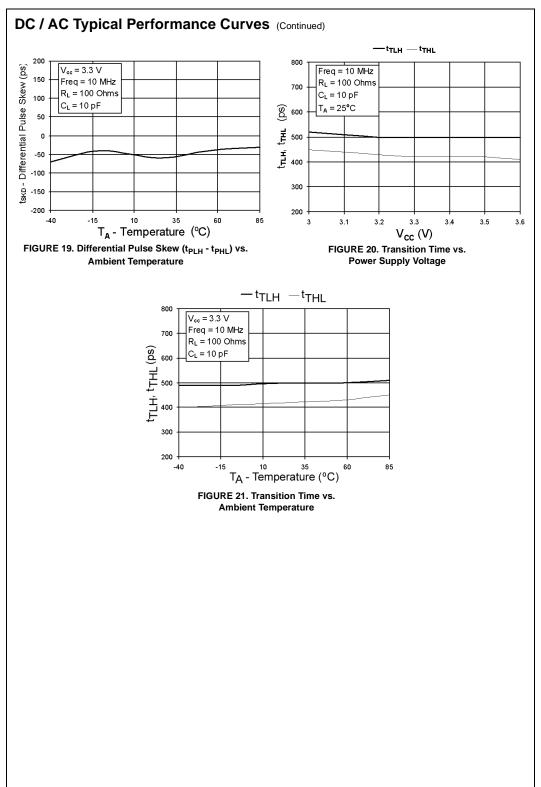


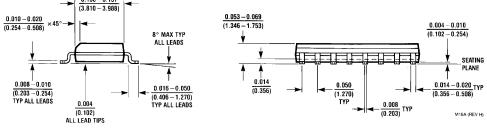
FIGURE 6. f<sub>MAX</sub> Test Circuit



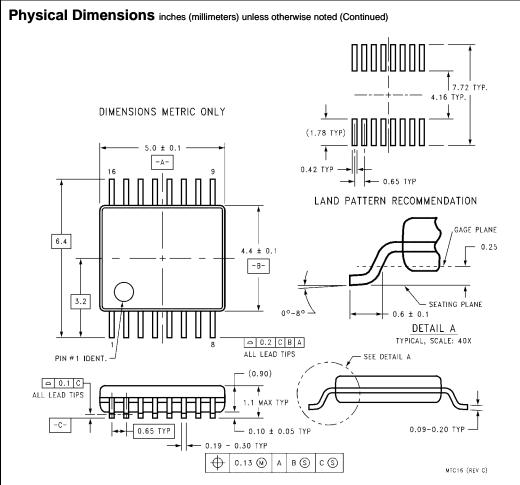




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16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow Package Number M16A



16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC16

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